

# Product / Process Change Notification



N° 2021-048-A

Dear Customer,

Please find attached our INFINEON Technologies PCN:

## Capacity expansion by introduction of an additional assembly and final test location for BGA 824N6

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **31 May 2021**
- Infineon aligns with the widely-recognized JEDEC STANDARD “**JESD46**“, which stipulates:  
“**Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.**”

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG  
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Chairman of the Supervisory Board: Dr. Wolfgang Eder  
Management Board: Dr. Reinhard Ploss (CEO), Dr. Helmut Gassel, Jochen Hanebeck, Constanze Hufenbecher, Dr. Sven Schneider  
Registered Office: Neubiberg  
Commercial Register: München HRB 126492

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► **Products affected:** Please refer to attached affected product list 1\_cip21048\_a

► **Detailed Change Information:**

**Subject:** Capacity expansion by introduction of an additional assembly and final test location at JCET Group Co., Ltd, Jiangyin, China for BGA 824N6

**Reason:** Expansion of assembly and test location to assure continuity and increase supply flexibility.

**Description:**

<u>Old</u>	<u>New</u>
<ul style="list-style-type: none"><li>■ Infineon Melaka, Infineon Technologies (Malaysia) Sdn. Bhd., Melaka, Malaysia</li></ul>	<ul style="list-style-type: none"><li>■ Infineon Melaka, Infineon Technologies (Malaysia) Sdn. Bhd., Melaka, Malaysia</li><li><i>or</i></li><li>■ Subcon JCET, JCET Group Co., Ltd, Jiangyin, China</li></ul>
<ul style="list-style-type: none"><li>■ Infineon Melaka packing = Tape &amp; Reel 15,000pcs</li></ul>	<ul style="list-style-type: none"><li>■ Infineon Melaka packing = Tape &amp; Reel 15,000pcs</li><li><i>or</i></li><li>■ Subcon JCET packing = Tape &amp; Reel 12,000pcs</li></ul>

► **Product Identification:**

1. Internal traceability : Baunumber, lot number, date code
2. External traceability : Marking and SP number (Please refer to attached 3\_cip21048\_a)

► **Impact of Change:**

**NO** change on electrical and thermal performance  
**NO** impact on the device reliability as proven via product qualification  
**NO** change in quality and device processability at customer end.  
Assembly processes are optimized to meet product performance according to already applied Infineon specification.

- The package outer dimension remains unchanged
- Product datasheet remain unchanged

► **Attachments:**

Affected product list : 1\_cip21048\_a  
Qualification test report : 2\_cip21048\_a  
Customer info package : 3\_cip21048\_a

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## ► Time Schedule:

- |                               |   |
|-------------------------------|---|
| ■ Final qualification report: | available   |
| ■ First samples available:    | available   |
| ■ Intended start of delivery: | 20-July-2021 or earlier, depending on customer's approval |

If you have any questions, please do not hesitate to contact your local Sales office.

**PCN N° 2021-048-A**

Capacity expansion by introduction of an additional assembly and final test location for BGA  
824N6



<b>Sales name</b>	<b>SP number</b>	<b>OPN</b>	<b>Package</b>
BGA 824N6 E6327	SP001079364	BGA824N6E6327XTSA1	PG-TSNP-6